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FH MONDAY

Dixon and Beetel Ink JV AMD and MediaTek CEA-Leti Spinoff Weaves RFID Agreement for Telecom. Collaborating on Wi-Fi 6E Chips, Raises €15m in Funding Networking Product MediaTek and AMD are How to create a more transparent Dixon Technologies (India) collaborating to co-engineer textile supply chain? Grenoble, Ltd has entered into joint industry leading Wi-Fi solutions, France-based embedded RFID venture (JV) agreement with starting with the AMD RZ600 startup Primo1D provides a UHF Beetel Teletech Ltd, pursuant Series Wi-Fi 6E modules RFID wire tag in a textile ribbon to which they will set up Dixon containing MediaTek's new that is embedded in the garment Filogic 330P chipset. The Filogic Electro Appliances Private Ltd during the production process. 330P chipset will power next-(JV company)-to be 51% Primo1D has just raised €15 generation AMD Ryzen-series owned by Dixon and 49% million to move to industrial scale laptop and desktop PCs in 2022 and address high-volume owned by Beetel. and beyond, delivering fast Wi-Fi markets. speeds with low latency and less interference from other signals. read more read more read more FutureHorizons TALK TO US Wireless Logic Acquires Nordic Cellular IoT SIM Partner Arkessa SiFive Unveils 64-Bit RISC-V Server Core **EVENTS** Silicon Chip Industry One of Nordic SiFive's just announced Performance P650 RISC-V Semiconductor's nRF9160 Seminar System-in-Package (SiP) processor core is aimed at -November 2021- London UK cellular IoT connectivity high-end servers and other partners, Arkessa, has been applications requiring large Industry Forecast Briefing acquired by an even larger arrays of multiple processor independent IoT connectivity - January 2022- London UK cores. and multi-SIM management DON'T MISS OUT.company, Wireless Logic BOOK NOW BY Group. CALLING +44 1732 740440 read more read more OR EMAIL mail@futuraharizana aam

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CEA-Leti Spinoff Weaves RFID Chips, Raises €15m in Funding

How to create a more transparent textile supply chain? Grenoble, France-based embedded RFID startup Primo1D provides a UHF RFID wire tag in a textile ribbon that is embedded in the garment during the production process. Primo1D has just raised €15 million to move to industrial scale and address high-volume markets.

Primo1D was founded in 2013 as a spinoff of the CEA-Leti research institute. "Connected objects and wearables were already hot topics at this time, and the industry was asking for a smart way to miniaturize and incorporate durable electronic components into textile or plastic materials," Emmanuel Arène, CEO and founder of Primo1D, told EE Times Europe. "CEA-Leti then developed the E-Thread technology, a platform to embed electronics into materials and objects."

Dixon and Beetel Ink JV Agreement for Telecom, Networking Product Manufacturing

Dixon Technologies (India) Ltd has entered into joint venture (JV) agreement with Beetel Teletech Ltd, pursuant to which they will set up Dixon Electro Appliances Private Ltd (JV company)—to be 51% owned by Dixon and 49% owned by Beetel.

The JV company has received approval under PLI scheme of Government of India for manufacturing of telecom and networking products in India and, in accordance with the same, will undertake manufacturing of telecom and networking products, inter-alia GPONs, ONTs, modems, routers, set top boxes, and IOT devices, to name a few, for the telecom sector/industry, including for Beetel and Airtel.

AMD and MediaTek Collaborating on Wi-Fi 6E Modules

MediaTek and AMD are collaborating to co-engineer industry leading Wi-Fi solutions, starting with the AMD RZ600 Series Wi-Fi 6E modules containing MediaTek's new Filogic 330P chipset. The Filogic 330P chipset will power next-generation AMD Ryzen-series laptop and desktop PCs in 2022 and beyond, delivering fast Wi-Fi speeds with low latency and less interference from other signals.

To optimize the AMD RZ600 Series Wi-Fi 6E modules with a focus on delivering seamless connectivity experiences for customers, AMD and MediaTek developed and certified PCIe and USB interfaces for modern sleep states and power management, which are vital elements of modern customer experiences. Further, the optimization process included stress testing and ensuring compatibility standards, which may ultimately reduce development time for OEM customers.

Wireless Logic Acquires Nordic Cellular IoT SIM Partner Arkessa

One of Nordic Semiconductor's nRF9160 System-in-Package (SiP) cellular IoT connectivity partners, Arkessa, has been acquired by an even larger independent IoT connectivity and multi-SIM management company, Wireless Logic Group.

Wireless Logic Group is said to have over 8 million IoT subscriptions active in over 165 countries, with collaborative partnerships that reach into more than 750 mobile networks across the globe. This includes direct access to 75 cellular Low Power Wide Area (LPWA) networks in 45 countries within Europe alone for both the NB-IoT and LTE-M flavors of cellular IoT wireless technology.

Although the Arkessa brand will remain for now, with its LPWA network expertise fully retained, Wireless Logic Group says the acquisition will give Nordic customers a "super-charged" expansion in global network access and an even wider choice of cellular IoT data and connectivity options.

SiFive Unveils 64-Bit RISC-V Server Core

SiFive's just announced Performance P650 RISC-V processor core is aimed at high-end servers and other applications requiring large arrays of multiple processor cores.

The P650 processor core is a 64-bit implementation of the RISC-V architecture with an out-of-order pipeline and advanced branch prediction. The new RISC-V core arrives months after SiFive introduced its Performance P550 processor core.

The P650 brings a pair of attributes placing it within the realm of high-end server processors. First, SiFive has made specific performance enhancements to the processor architecture, including a 4-wide instruction dispatch (increased from the P550 core's 3-wide dispatch) to three execution units. The Performance P650 core has a 13-stage load/store pipeline and a separate, 10-stage integer execution pipeline.